

	Type	L #	Hits	Search Text
1	BRS	L1	322665	(( semiconductor or wafer\$1 or chip\$1 or ( integrated adj circuit\$3 ) or ic\$2 ) near7 ( fab\$8 or manufactur\$3 or processing )).ti,ab.
2	BRS	L2	330	1 and ( skip\$ near7 ( process\$3 or step\$1 or judgement ) )
3	BRS	L3	23	1 and ( skip\$ near7 ( process\$3 or step\$1 or judgement ) )
4	BRS	L4	307	1 and ( skip\$ near7 ( process\$3 or step\$1 or judgement ) )
5	BRS	L5	18	( (( semiconductor or wafer\$1 or chip\$1 or ( integrated adj circuit\$3 ) or ic\$2 ) near7 ( fab\$8 or manufactur\$3 or processing )).ti,ab.) and ( skip\$ near7 ( process\$3 or step\$1 ) near7 ( judg\$5 or determin\$3 ) )
6	BRS	L6	0	( (( semiconductor or wafer\$1 or chip\$1 or ( integrated adj circuit\$3 ) or ic\$2 ) near7 ( fab\$8 or manufactur\$3 or processing )).ti,ab.) and ( skip\$ near7 ( process\$3 or step\$1 ) near7 ( judg\$5 or determin\$3 ) )
7	BRS	L7	322828	(( semiconductor or wafer\$1 or chip\$1 or ( integrated adj circuit\$3 ) or ic\$2 ) near7 ( fab\$8 or manufactur\$3 or processing )).ti,ab.
8	BRS	L8	18	( (( semiconductor or wafer\$1 or chip\$1 or ( integrated adj circuit\$3 ) or ic\$2 ) near7 ( fab\$8 or manufactur\$3 or processing )).ti,ab.) and ( skip\$ near7 ( process\$3 or step\$1 ) near7 ( judg\$5 or determin\$3 ) )

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	DBs	Time Stamp	Comments	Error Definition	Errors
1	USPAT; US-PPGPUB ; EPO; JPO; DERWENT	2004/09/08 15:18			0
2	USPAT; US-PPGPUB ; EPO; JPO; DERWENT	2004/09/08 15:20			0
3	EPO; JPO; DERWENT	2004/09/08 15:21			0
4	USPAT; US-PPGPUB	2004/09/08 15:21			0
5	USPAT; US-PPGPUB ; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:22			0
6	EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:23			0
7	USPAT; US-PPGPUB ; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:24			0
8	USPAT; US-PPGPUB ; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:24			0

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		Type	L #	Hits	Search Text
9	BRS	L9	8		( (( semiconductor or wafer\$1 or chip\$1 or ( integrated adj circuit\$3 ) or ic\$2 ) near7 ( fab\$8 or manufactur\$3 or processing )).ti,ab.) and (( bypass\$3 or ( by adj pass\$3 ) ) near7 ( process\$3 or step\$1 ) near7 ( judg\$5 or determin\$3 ))
10	BRS	L10	10		( (( semiconductor or wafer\$1 or chip\$1 or ( integrated adj circuit\$3 ) or ic\$2 ) near7 ( fab\$8 or manufactur\$3 or processing )).ti,ab.) and (( omit\$5 or omission ) near7 ( process\$3 or step\$1 ) near7 ( judg\$5 or determin\$3 ))
11	BRS	L11	47		( (( semiconductor or wafer\$1 or chip\$1 or ( integrated adj circuit\$3 ) or ic\$2 ) near7 ( fab\$8 or manufactur\$3 or processing )).ti,ab.) and (( eliminat\$4 ) near7 ( process\$3 or step\$1 ) near7 ( judg\$5 or determin\$3 ))

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	DBs	Time Stamp	Components	Error Definition	Errors
9	USPAT; US-PPGPUB ; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:25			0
10	USPAT; US-PPGPUB ; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:26			0
11	USPAT; US-PPGPUB ; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:26			0

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